Plastic Packages for Integrated Circuits

Package Outline Drawing
L10.3x3B
10 LEAD THIN DUAL FLAT PACKAGE (TDFN) WITH E-PAD
Rev 4, 4/15

1. Dimensions are in millimeters. Dimensions in ( ) for Reference Only.
2. Dimensioning and tolerancing conform to AMSE Y14.5m-1994.
3. Unless otherwise specified, tolerance: Decimal ± 0.05
4. Tiebar shown (if present) is a non-functional feature and may be located on any of the 4 sides (or ends).
5. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.

NOTES:

TOP VIEW

BOTTOM VIEW

SIDE VIEW

TYPICAL RECOMMENDED LAND PATTERN

INDEX AREA

PIN #1 INDEX AREA

SEATING PLANE

SEE DETAIL "X"

DETAIL "X"